



## Material Content Data Sheet



Sales Product Name	TLE7233G			Issued		28. August 2013		
MA#	MA000982394							
Package	PG-SSOP-24-5			Weight*		146.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.214	2.19	2.19	21929	21929
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		425	
	non noble metal	iron	7439-89-6	1.245	0.85		8497	
	non noble metal	copper	7440-50-8	50.568	34.50	35.40	345027	354055
wire	noble metal	gold	7440-57-5	0.592	0.40	0.40	4038	4038
encapsulation	organic material	carbon black	1333-86-4	0.175	0.12		1192	
	plastics	epoxy resin	-	8.035	5.48		54822	
	inorganic material	silicondioxide	60676-86-0	79.127	54.00	59.60	539881	595895
leadfinish	non noble metal	tin	7440-31-5	1.680	1.15	1.15	11461	11461
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2492	2492
glue	plastics	acrylic resin	-	0.327	0.22		2229	
	noble metal	silver	7440-22-4	1.158	0.79	1.01	7901	10130
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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